

**A SELECTIVELY GOLD PLATED PRINTED CIRCUIT BOARD
AND METHOD FOR MANUFACTURE THEREOF**

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Abstract of the Disclosure

10 A method (100) for selectively gold plating pads (202,204,206,208)
on a Printed Circuit Board (PCB) provides the PCB with at least two
thicknesses of gold plated pads. One or more pads (202,204) on the PCB
are first plated with gold (302,304) and then masked with a protective layer
to prevent detrimental damage from subsequent gold plating. The masking
provides a set of masked pads and a set of unmasked pads. Unmasked
15 pads are then plated with a different thickness of gold (506,508) compared
to the gold (302,304) on the masked pads. Removal of the protective layer
provides the PCB with at least two thicknesses of gold (302,304,506,508)
on the pads (202,204,206,208).

FIG. 6 accompanies this abstract.

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